

January 29, 1998

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### QUICK REFERENCE DATA

- $V_R = 600 - 1000V$
- $I_F = 2.0A$
- $t_{rr} = 2.5\mu S$
- $I_R = 1.0\mu A$

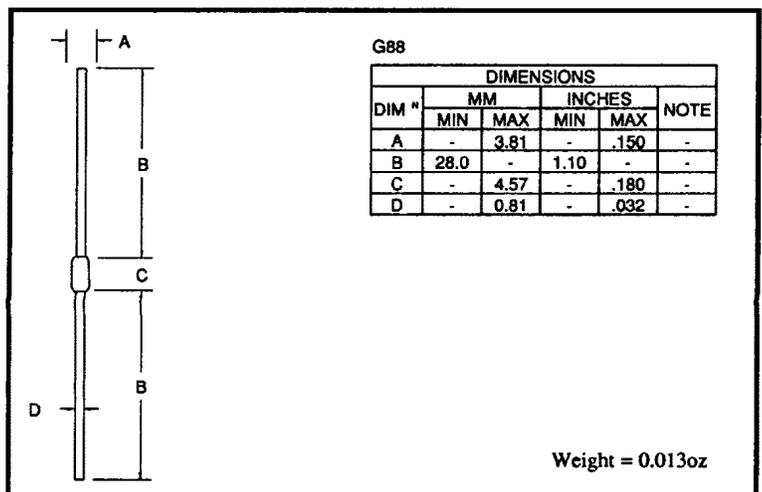
### AXIAL LEADED HERMETICALLY SEALED STANDARD RECOVERY RECTIFIER DIODE

- Avalanche capability
- High thermal shock resistance
- Glass passivated for hermetic sealing
- Low reverse leakage currents
- Low forward voltage drop

### ABSOLUTE MAXIMUM RATINGS (@ 25°C unless otherwise specified)

	Symbol	PM6	PM8	PM0	Unit
Working reverse voltage	$V_{RWM}$	600	800	1000	V
Repetitive reverse voltage	$V_{RRM}$	600	800	1000	V
Surge reverse voltage	$V_{RSM}$	650	900	1100	V
Average forward current (@ 55°C, lead length 0.375")	$I_F$	←	2.0	→	A
Repetitive surge current (@ 55°C in free air, lead length 0.375")	$I_{FRM}$	←	12.0	→	A
Non-repetitive surge current ( $t_p = 8.3mS$ , @ $V_R$ & $T_{jmax}$ )	$I_{FSM}$	←	50	→	A
Storage temperature range	$T_{stg}$	←	-65 to +175	→	°C
Operating temperature range	$T_{oper}$	←	-65 to +175	→	°C

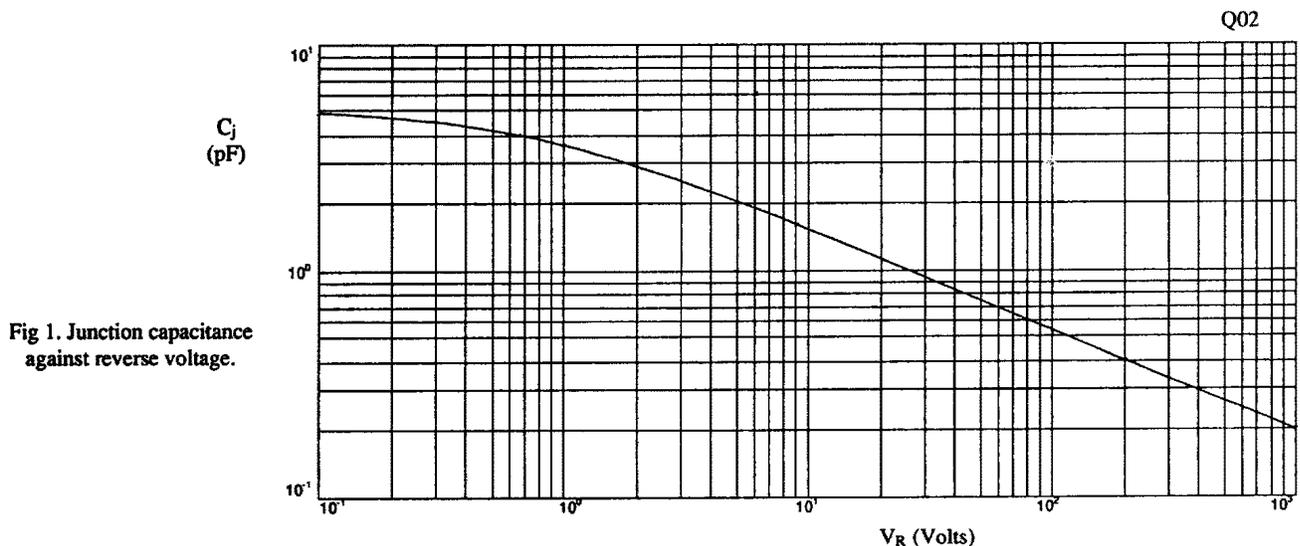
### MECHANICAL



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### CHARACTERISTICS (@ 25°C unless otherwise specified)

	Symbol	PM6	PM8	PM0	Unit
Average forward current for sine wave - max. pcb mounted; $T_A = 55^\circ\text{C}$ - max. $L = 3/8"$ ; $T_L = 55^\circ\text{C}$	$I_{F(AV)}$	← 1.1 →			A
	$I_{F(AV)}$	← 2.0 →			A
$I^2t$ for fusing ( $t = 8.3\text{ms}$ ) max.	$I^2t$	← 12.0 →			$\text{A}^2\text{S}$
Forward voltage drop max. @ $I_F = 1.00\text{A}$ , $T_j = 25^\circ\text{C}$	$V_F$	← 1.0 →			V
Reverse current max. @ $V_{RWM}$ , $T_j = 25^\circ\text{C}$	$I_R$	← 1.0 →			$\mu\text{A}$
@ $V_{RWM}$ , $T_j = 100^\circ\text{C}$	$I_R$	← 10 →			$\mu\text{A}$
Reverse recovery time typ. 0.5A $I_F$ to 1.0A $I_R$ . Recovers to 0.25A $I_{RR}$ .	$t_{rr}$	← 2.5 →			$\mu\text{S}$
Junction capacitance typ. @ $V_R = 5\text{V}$ , $f = 1\text{MHz}$	$C_j$	← 20 →			$\text{pF}$
Thermal resistance - junction to lead Lead length = 0.375"	$R_{\theta JL}$	← 47 →			$^\circ\text{C/W}$
Lead length = 0"	$R_{\theta JL}$	← 19 →			$^\circ\text{C/W}$
Thermal resistance - junction to amb. on 0.06" thick pcb. 1oz copper.	$R_{\theta JA}$	← 100 →			$^\circ\text{C/W}$



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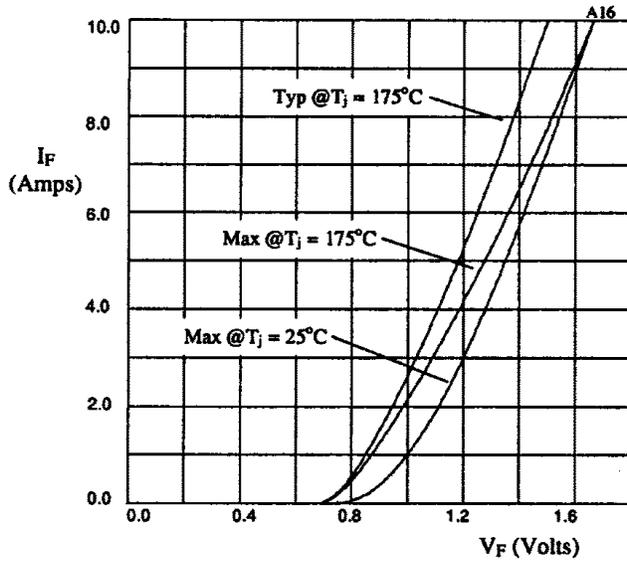


Fig 2. Forward voltage drop as a function of forward current.

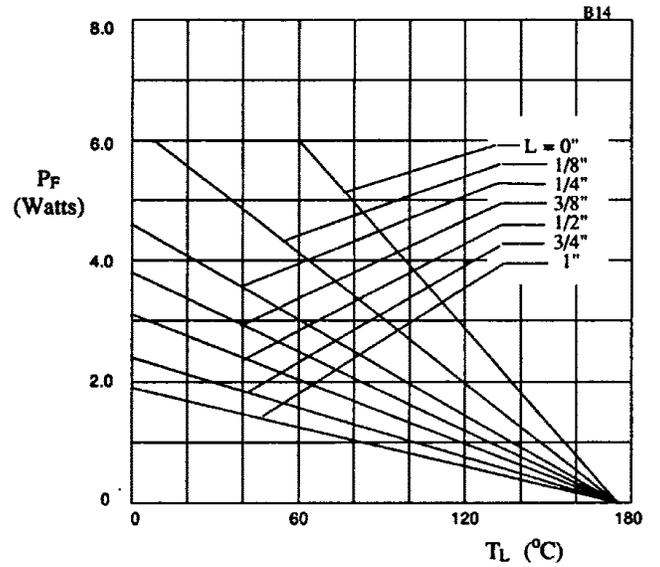


Fig 3. Maximum power versus lead temperature.

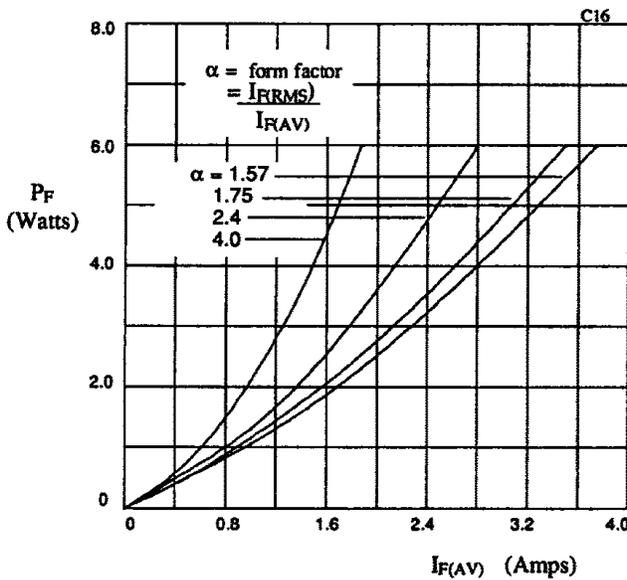


Fig 4. Forward power dissipation as a function of forward current, for sinusoidal operation.

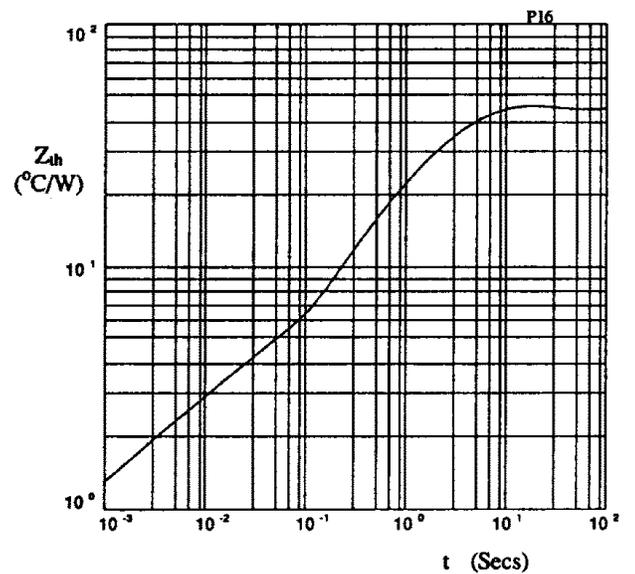


Fig 5. Transient thermal impedance characteristic.